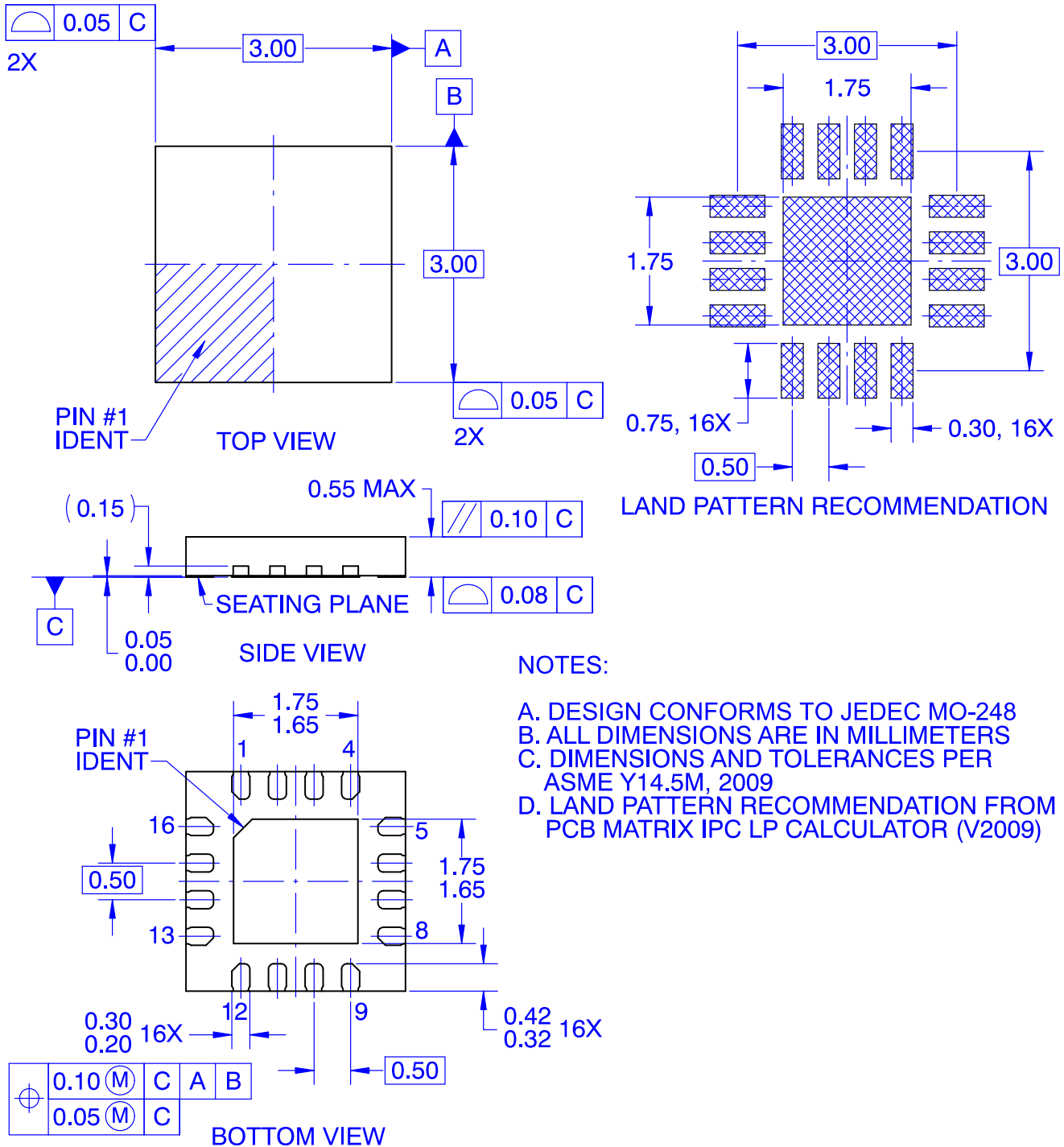


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

UQFN16 3x3, 0.5P
CASE 523BB
ISSUE O

DATE 31 OCT 2016



NOTES:

- A. DESIGN CONFORMS TO JEDEC MO-248
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009
- D. LAND PATTERN RECOMMENDATION FROM PCB MATRIX IPC LP CALCULATOR (V2009)

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	UQFN16 3x3, 0.5P	PAGE 1 OF 2

